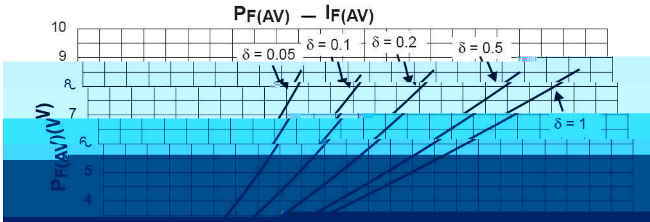
/ Absolute Maximum Ratings(Ta=25)

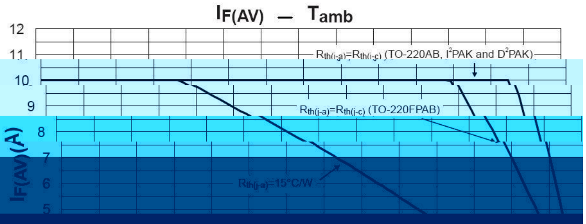
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
RMS Forward Current	$I_{F(RMS)}$	30	A
Average Forward Current	$I_{F(AV)}$	10	A
Average Forward Current	$I_{F(AV)}$ total device	20	A
Non Repetitive Peak Surge Current	I_{FSM}	180	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	1.5	℃/W
Junction Temperature Range	T_j	150	℃
Storage Temperature Range	T_{stg}	-55 150	℃

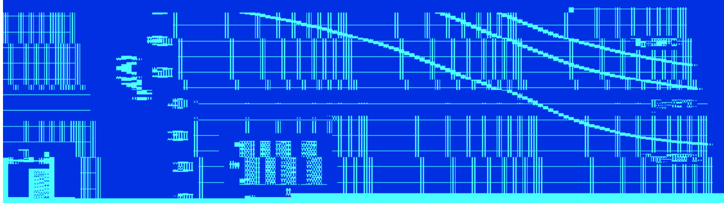
/ Electrical Characteristics(Ta=25)

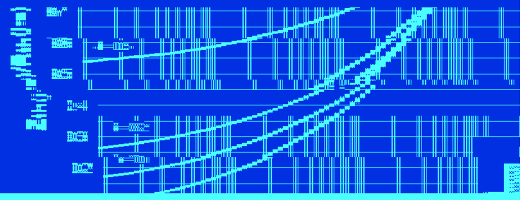
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F =10A(Tc=25℃)			0.9	V
		I_F =10A(Tc=125℃)		0.69	0.75	V
		I_F =20A(Tc=25℃)			1.0	V
		I_F =20A(Tc=125℃)		0.79	0.86	V
Instantaneous Reverse Current	I_R	V_R=150V(Tc=25℃)			5.0	μA
		V_R=150V(Tc=125℃)			5.0	mA
Critical rate of rise of reverse voltage	dv/dt				10000	V/μs

/ Electrical Characteristic Curve

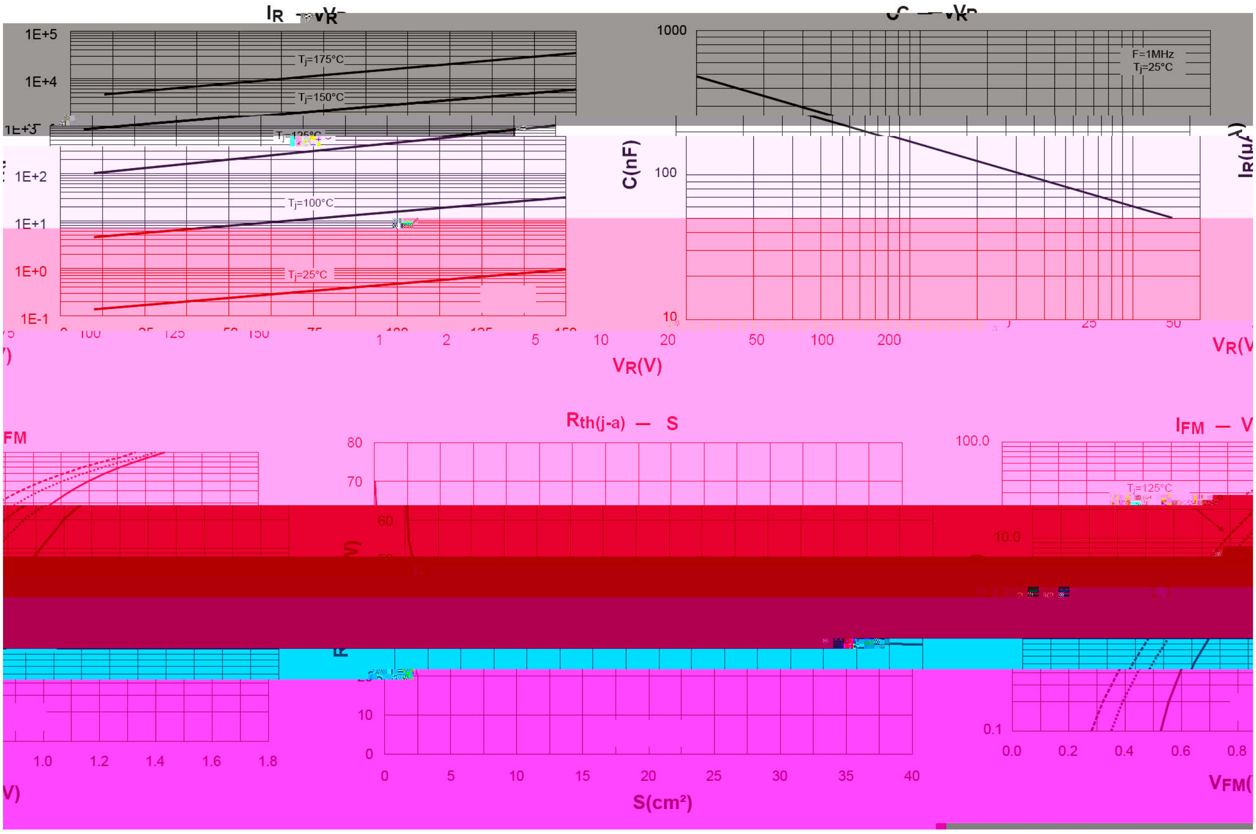




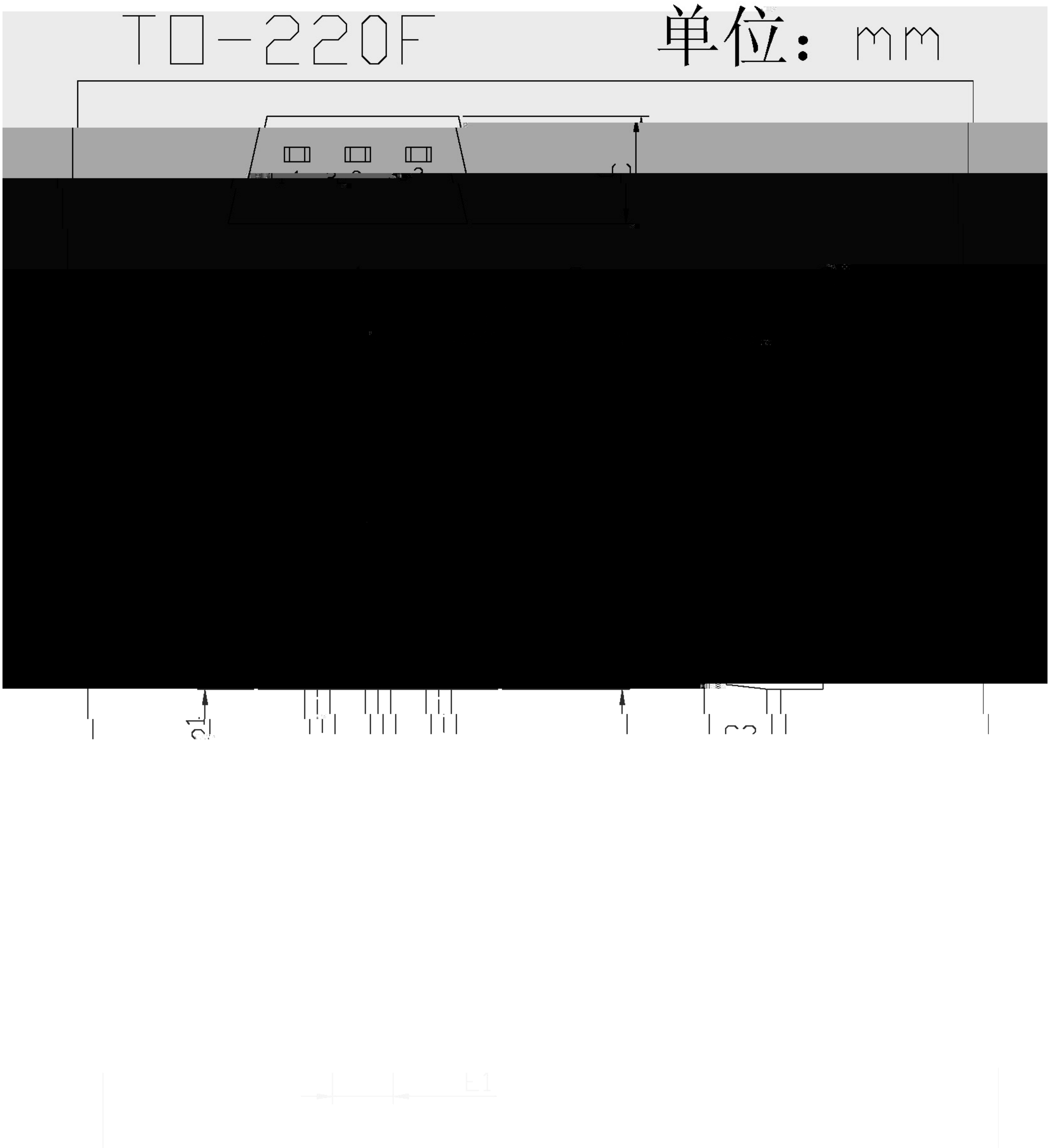




/ Electrical Characteristic Curve



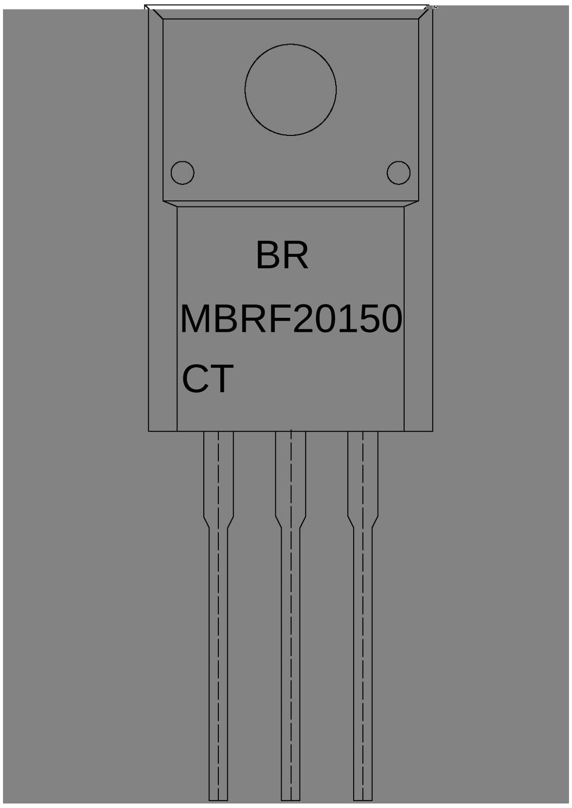
/ Package Dimensions



[redacted]

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.3	4.7	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.75
B	14.7	15.3	E	2.29	2.79
B1	3.8	4.0	E1	2.29	2.79
B2	2.9	3.1	C1	2.5	2.9
R	3.0	3.4	C2	2.5	2.7
b	12.5	13.5	c	0.5	0.7

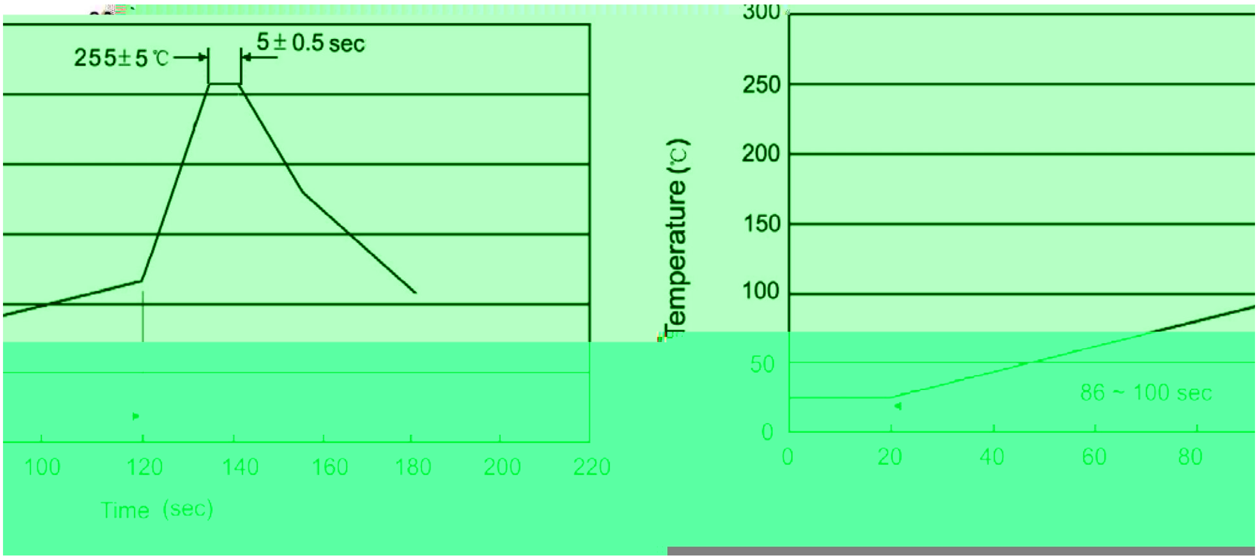
/ Marking Instructions



Note:

BR:	Company Code
MBRF20150:	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

2 255 5 5 0.5sec;

3 2 10 /sec.

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255 5 , Duration:5 0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec.

Temp.:270±5℃ Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension		(unit mm^3)

/ TUBE

Package Type	Units					Dimension		(unit mm^3)

/ Notices